

	L #	Hits	Search Text	DBs
1	L1	119120	mold\$4.ti,ab.	US- PGPUB; USPAT
2	L2	50822	etch\$4.ti,ab.	US- PGPUB; USPAT
3	L3	158427	(hole or orifice).ti,ab.	US- PGPUB; USPAT
4	L4	68	1 and 2 and 3	US- PGPUB; USPAT
5	L5	105858	(silicon or wafer).ti,ab.	US- PGPUB; USPAT
6	L6	105	1 and 2 and 5	US- PGPUB; USPAT
7	L7	87	6 not 4	US- PGPUB; USPAT
8	L8	336695	(substrate or wafer or silicon).ti,ab.	US- PGPUB; USPAT
9	L9	302350	(rear or back or backside or (other or second or reverse or bottom) adj2 (side or surface)).ti,ab.	US- PGPUB; USPAT
10	L10	12530	8 near5 9	US- PGPUB; USPAT
11	L11	313	1 and 10	US- PGPUB; USPAT
12	L12	11	2 and 11	US- PGPUB; USPAT
13	L13	2666533	(rear or back or backside or (other or second or reverse or bottom) adj2 (side or surface))	US- PGPUB; USPAT
14	L14	1165859	(substrate or wafer or silicon)	US- PGPUB; USPAT
15	L15	125488	13 near5 14	US- PGPUB; USPAT

	L #	Hits	Search Text	DBs
16	L16	351910	etch\$4	US-PGPUB; USPAT
17	L17	26878	15 same 16	US-PGPUB; USPAT
18	L18	359	1 and 17	US-PGPUB; USPAT
19	L19	686075	mold\$4	US-PGPUB; USPAT
20	L20	564	17 same 19	US-PGPUB; USPAT
21	L21	18989	15 with 16	US-PGPUB; USPAT
22	L23	288	19 with 21	US-PGPUB; USPAT
23	L24	41	1 and 23	US-PGPUB; USPAT
24	L25	49604	((metal\$4 near3 deposit\$6) or electro or electroform\$8 or electrocoat\$8 or electrodeposit\$8 or electrolytic\$8).ti,ab.	US-PGPUB; USPAT
25	L26	28274	(nickel or ni).ti,ab.	US-PGPUB; USPAT
26	L27	58	1 and 2 and (25 or 26)	US-PGPUB; USPAT
27	L28	352742	((metal\$4 near3 deposit\$6) or electro or electroform\$8 or electrocoat\$8 or electrodeposit\$8 or electrolytic\$8)	US-PGPUB; USPAT
28	L29	387122	(nickel or ni)	US-PGPUB; USPAT
29	L30	2385	17 same (28 or 29)	US-PGPUB; USPAT
30	L31	56	1 and 30	US-PGPUB; USPAT

	L #	Hits	Search Text	DBs
31	L33	1088	430/320.ccls.	US-PGPUB; USPAT
32	L34	25	1 and 2 and 33	US-PGPUB; USPAT
33	L35	21	1 and 15 and 33	US-PGPUB; USPAT
34	L36	1629	430/323.ccls.	US-PGPUB; USPAT
35	L37	35	1 and 36	US-PGPUB; USPAT
36	L38	1357	216/2,39.ccls.	US-PGPUB; USPAT
37	L39	40	1 and 38	US-PGPUB; USPAT
38	L40	241	205/70.ccls.	US-PGPUB; USPAT
39	L41	4	10 and 40	US-PGPUB; USPAT
40	L42	1225	264/219.ccls.	US-PGPUB; USPAT
41	L43	4	10 and 42	US-PGPUB; USPAT
42	L44	8	gmur-max\$.in.	US-PGPUB; USPAT
43	L45	2	fassler-thomas\$.in.	US-PGPUB; USPAT
44	L46	9	44 or 45	US-PGPUB; USPAT
45	L47	27	(40 or 42) and 5	US-PGPUB; USPAT

	L #	Hits	Search Text	DBs
46	L48	163086	mold\$4.clm.	US-PGPUB; USPAT
47	L49	35722	etch\$4.clm.	US-PGPUB
48	L51	177574	(substrate or wafer or silicon).clm.	US-PGPUB
49	L52	178463	(rear or back or backside or (other or second or reverse or bottom) adj2 (side or surface)).clm.	US-PGPUB
50	L53	15085	51 near5 52	US-PGPUB
51	L54	192	48 and 49 and 53	US-PGPUB
52	L55	96595	(hole or orifice).clm.	US-PGPUB
53	L56	61	54 and 55	US-PGPUB
54	L57	637	53 near5 55	US-PGPUB
55	L58	52	48 and 57	US-PGPUB
56	L59	36	58 not 56	US-PGPUB